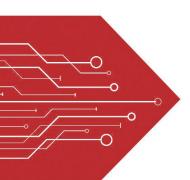
# MSKSEMI















**ESD** 

TVS

TSS

MOV

**GDT** 

**PLED** 

# Brodnet data speet

www.msksemi.com



SOT-23

#### **Features**

- 300 Watts peak pulse power (tp =  $8/20\mu$ s
- ) Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Protection two data lines:
- IEC 61000-4-2 ±30kV contact ±30kV air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 15A (8/20μs)

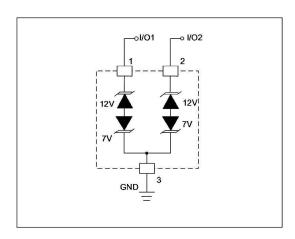
#### **Mechanical Data**

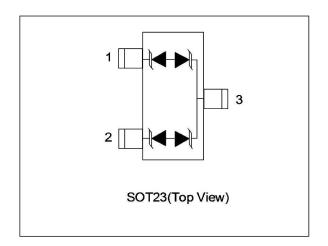
- SOT-23 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

## **Applications**

- Dataline
- Automatic Teller Machines
- Net works
- Power line

# Schematic & PIN Configuration









**Absolute Maximum Rating** 

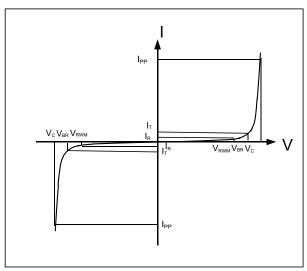
Rating	Symbol	Value	Units
Peak Pulse Power ( t <sub>p</sub> =8/20μs )	P <sub>PP</sub>	300	Watts
Peak Pulse Current ( t <sub>p</sub> =8/20μs ) (note1)	$I_{pp}$	18	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	30 30	kV
Lead Soldering Temperature	$T_{ m L}$	260(10seconds)	$^{\circ}$
Junction Temperature	T <sub>J</sub>	-55 to + 125	°C
Storage Temperature	$T_{stg}$	-55 to + 125	°C

## **Electrical Characteristics**

			Pins 1 to 3 and 2 to 3 (12V TVS)			Pins 3 to 1 and 3 to 2 (7V TVS)			
Parameter	Symbol	Conditions	Min	Typical	Max	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>				12			7	V
Reverse Breakdown Voltage	$V_{\scriptsize BR}$	IT=1mA	13.5		16	7.5		9.5	V
Reverse Leakage Current	Ir	VR=VRWM			1			1	μΑ
Clamping Voltage	Vc	IPP=15A,tp=8/20μs		18					V
Clamping Voltage	Vc	IPP=18A,tp=8/20μs					14		V
Junction Capacitance	Cj	$V_R = 0V, f = 1MHz$		27			35		pF

# Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter	
Ірр	Maximum Reverse Peak Pulse Current	
Vc	Clamping Voltage @ Ipp	
V <sub>RWM</sub>	Working Peak Reverse Voltage	
IR	Maximum Reverse Leakage Current @ VRWM	
V <sub>BR</sub>	Breakdown Voltage @ IT	
Iτ	Test Current	



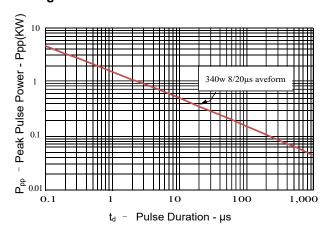
Note:.  $8/20\mu s$  pulse waveform.





# **Typical Characteristics**

Figure 1: Peak Pulse Power vs. Pulse Time



**Figure 2: Power Derating Curve** 

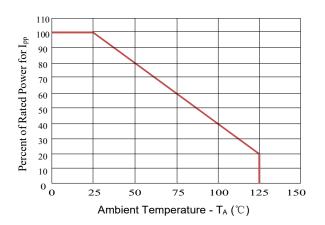


Figure3: Pulse Waveform

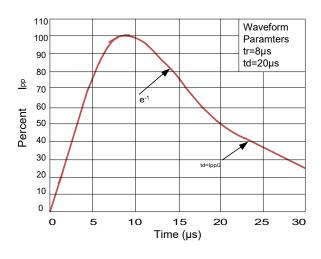
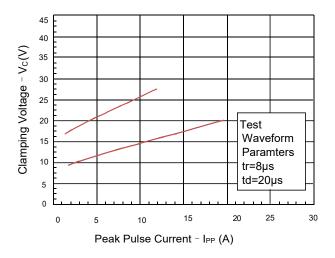


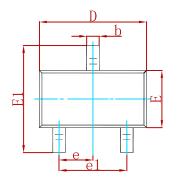
Figure 4: Clamping Voltage vs.lpp

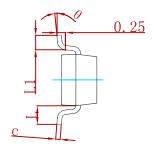


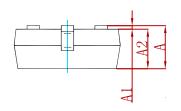




#### **PACKAGE MECHANICAL DATA**

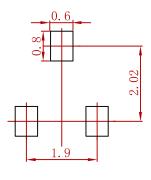






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# **Suggested Pad Layout**



- 1.Controlling dimension:in millimeters.2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
SDT23C712L02-MS	SOT-23	3000



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